

Developing Transition Metal Oxide-Based Carrier-Selective Contacts for Non-Epitaxial InP Solar Cells

Anish Chaluvadi¹, Luksa Kujovic², Adam Law², John M. Walls², Hannah Joyce³, Louise Hirst^{1,4}

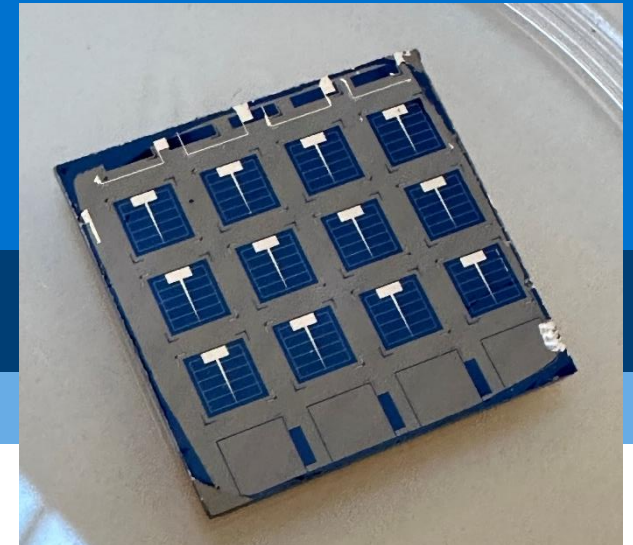
¹Department of Materials Science and Metallurgy, University of Cambridge

²Centre for Renewable Energy Systems Technology, Loughborough University

³Department of Engineering, University of Cambridge

⁴Cavendish Laboratory, Department of Physics, University of Cambridge

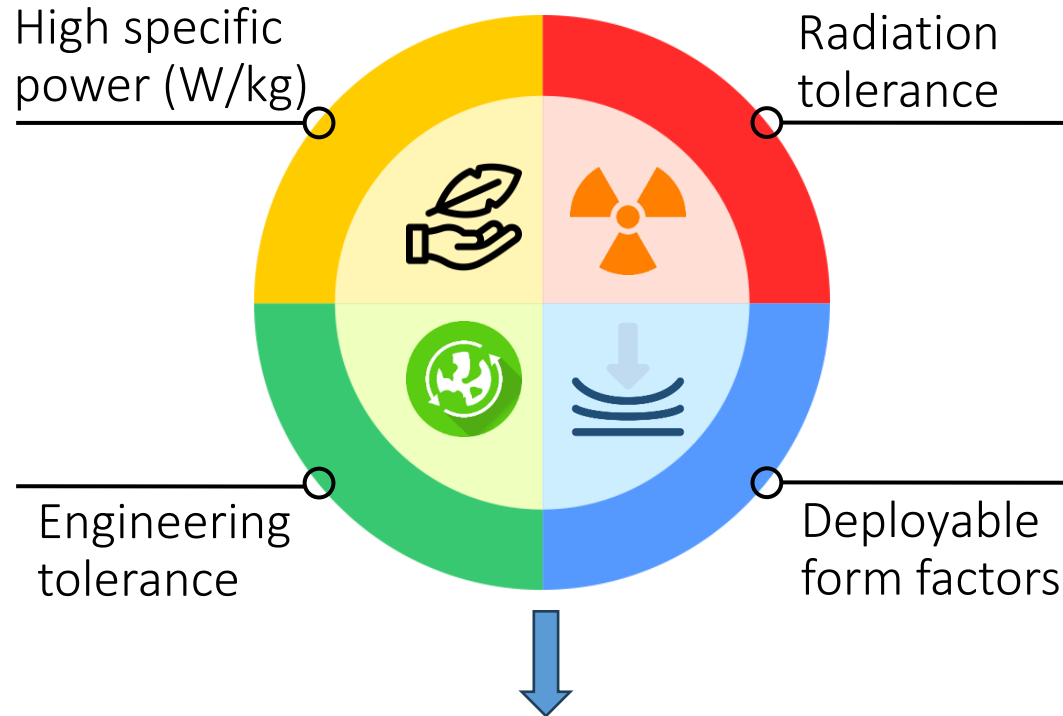
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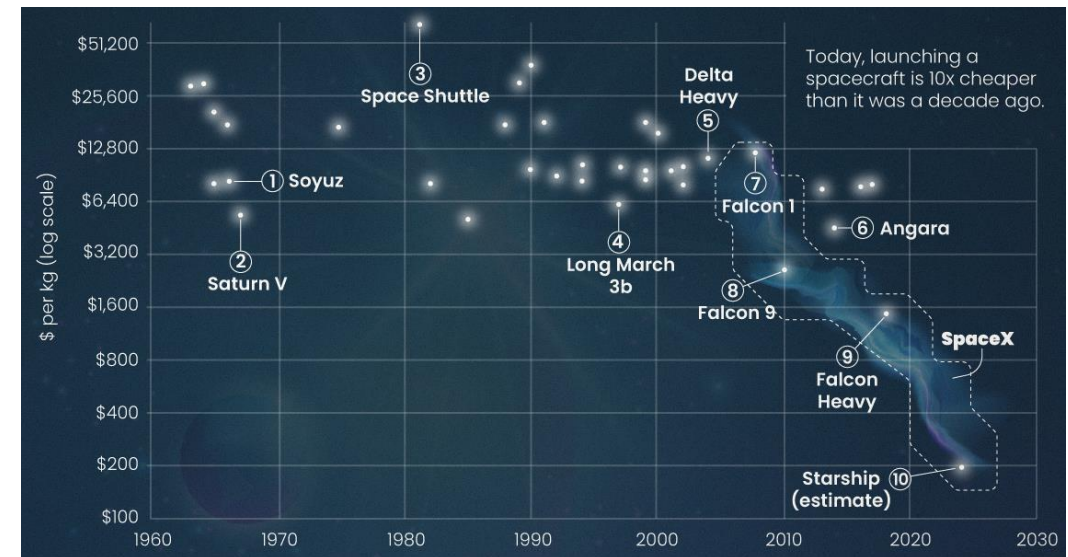
Challenges in Space Solar: Cost, Scalability & Radiation



Unique Requirements of Space



Exponentially falling launch costs have led to hardware becoming a significant cost bottleneck



Solar arrays and power subsystems represent **20–40% of satellite hardware costs**, especially for SmallSats and megaconstellations²



Rethinking III-V Solar Fabrication

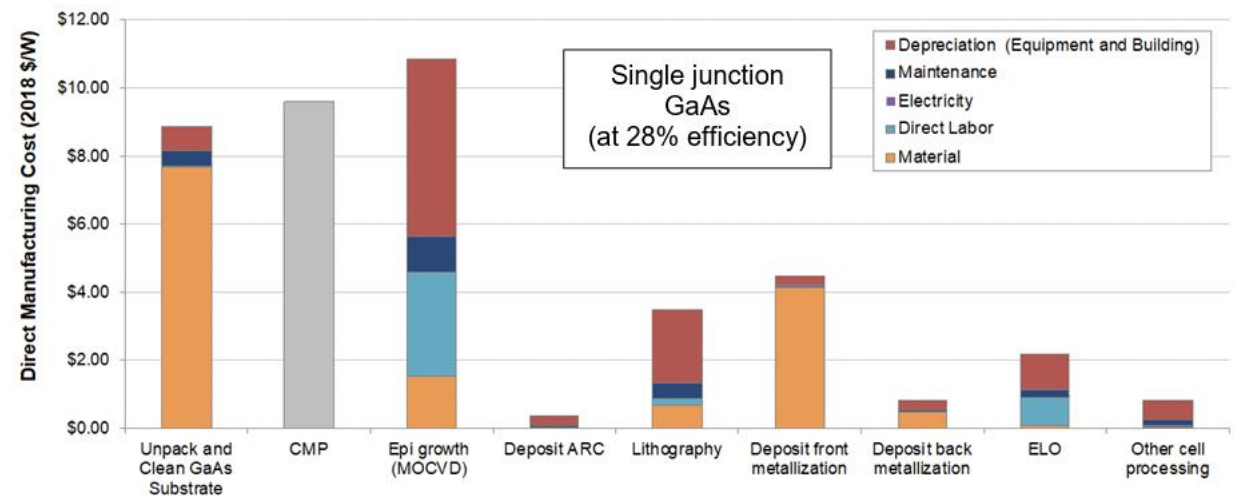


Traditional III-V solar cells cost \$60-100/W, two orders of magnitude greater than terrestrial Si³

- 💰 High-cost, low-throughput epitaxial growth
- 🔧 Complex post-processing and materials
 - Limited substrate reuse techniques
 - Metallization



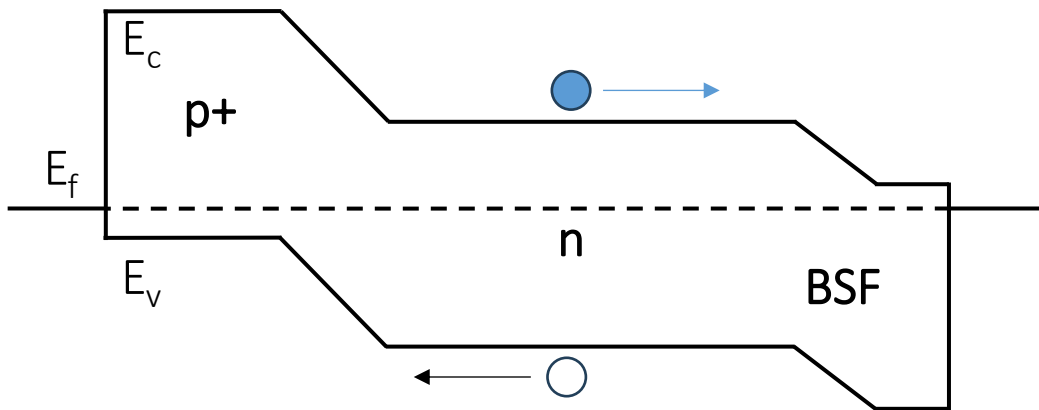
Current epitaxial techniques are intractable for cost-sensitive space applications



Rethinking III-V Solar Fabrication

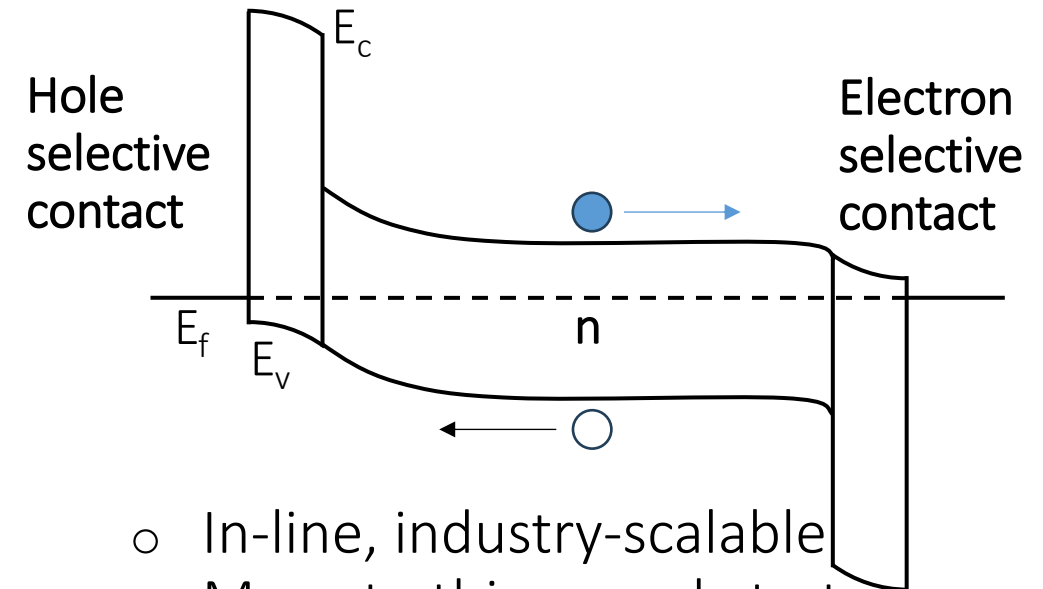
Reframing III-V device fabrication by **prioritizing cost-effective, scalable** processes which are compatible with next-generation, novel architectures

Homojunction formation
through epitaxial doping



- Small batch, low-throughput⁴
- Complex growth process
- Variable doping profile

Heterojunction formation
through carrier-selective contacts



- In-line, industry-scalable
- Move to thinner substrates

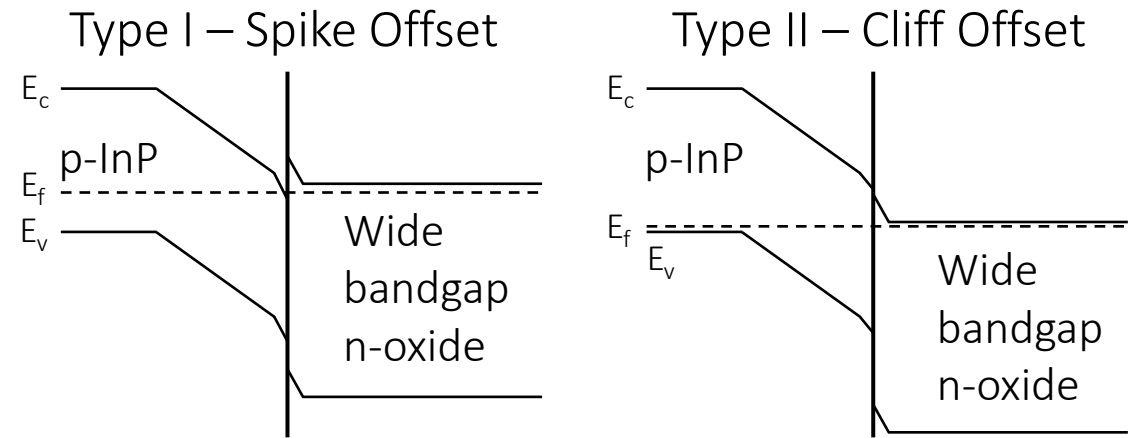
Transition Metal Oxides for Heterojunction Solar Cells



Offers efficient carrier selectivity with unique material and process advantages

- Potential for excellent **interface passivation**
- Potential for **low-temperature, high-throughput techniques** like sputtering
- No lattice-matching or heavy diffusion doping
- Usage of **Earth-abundant, low-cost** materials

Demonstrated at industrial scale for Si heterojunction solar cells



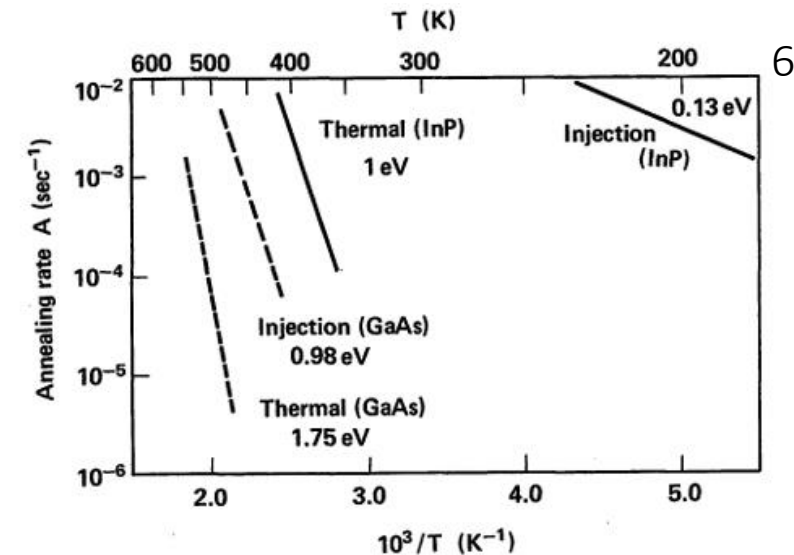
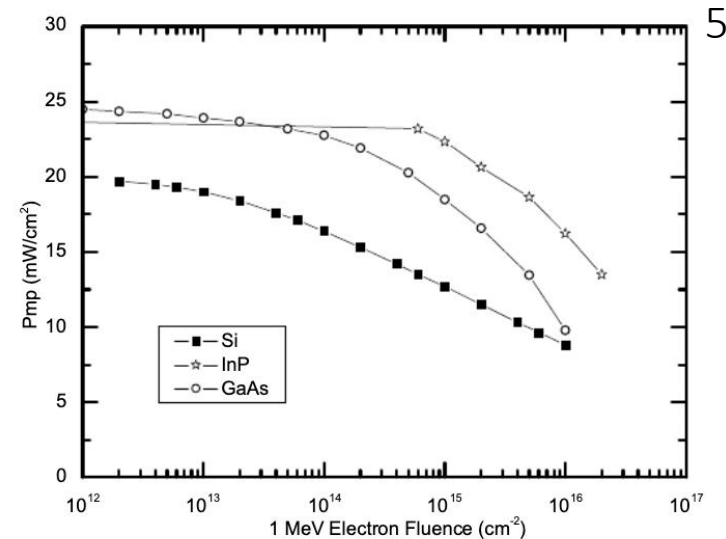
InP Offers High Defect Tolerance



Radiation Tolerance

- Non-ionizing energy loss (NIEL) values for InP ($\sim 10^{-2}$ MeV cm²/g for 3 MeV protons) are the lowest amongst space solar cell materials⁵
- Lower deep-level defect formation energy⁶
- Higher rate of room-temperature and minority-carrier injection enhanced annealing⁶

Growth Tolerance

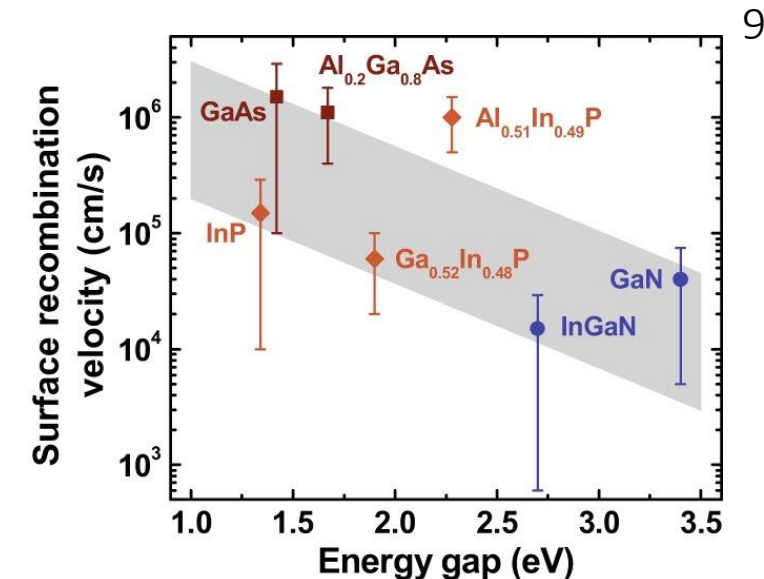
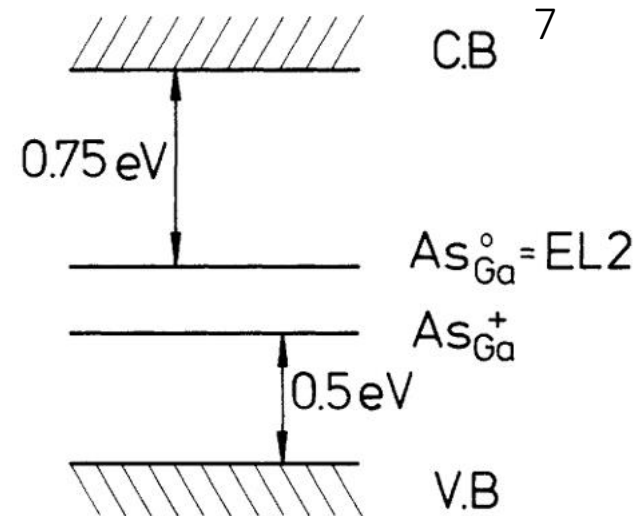


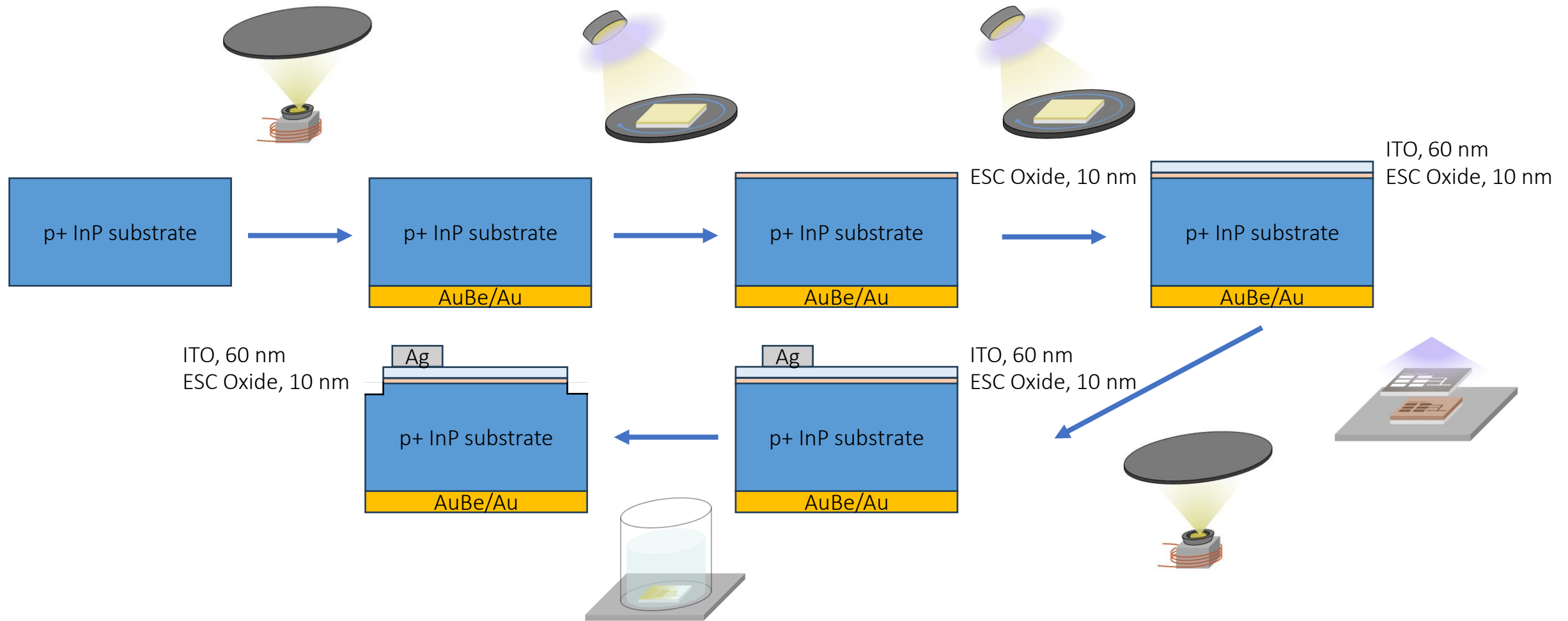
InP Offers High Defect Tolerance

Radiation Tolerance

- Lower thermal expansion coefficient exhibiting better stability during crystal growth, resulting in **fewer defects**⁷
 - No process limiting EL2 defect as compared to GaAs
- Longer minority carrier diffusion lengths and **low surface recombination velocity**^{6,8,9}

Growth Tolerance



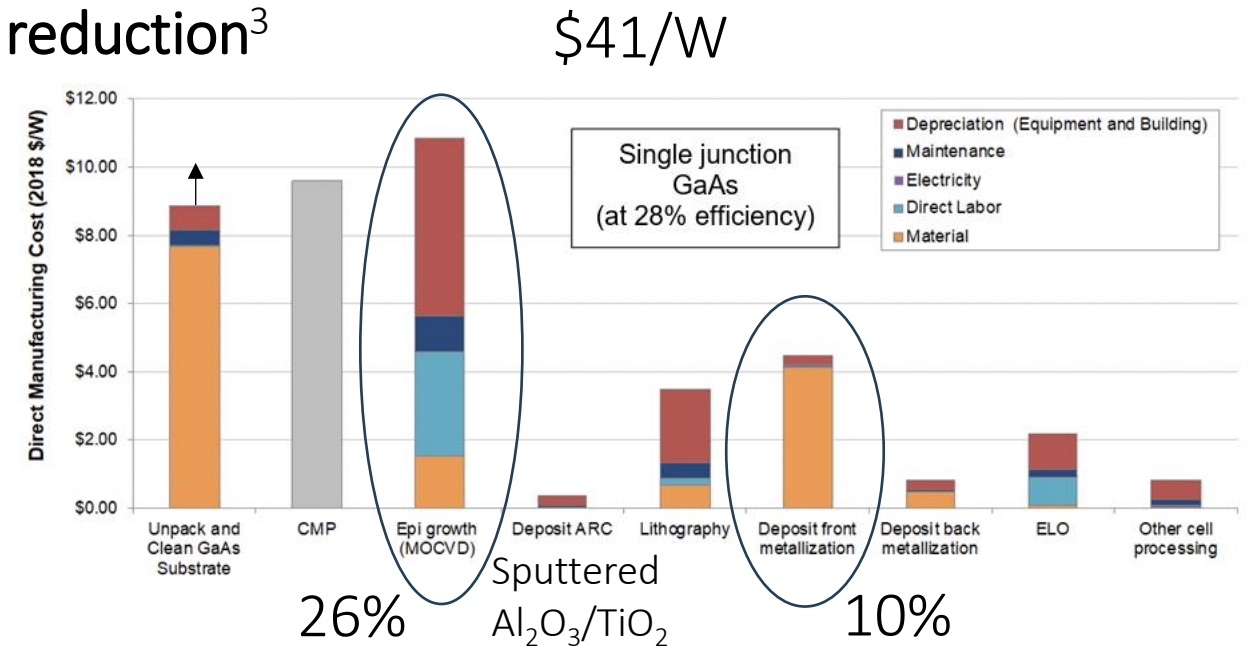


Aim to target **two key, highlighted areas of cost reduction**³

- Epitaxial growth costs
- Metallization

Assumptions

- Thinner substrates will have a similar effect on substrate cost as ELO reuse processing
- 20% AM1.5 efficient fully sputtered architecture is achievable



Reduced layer growth cost from \$11/W to \$1.50/W

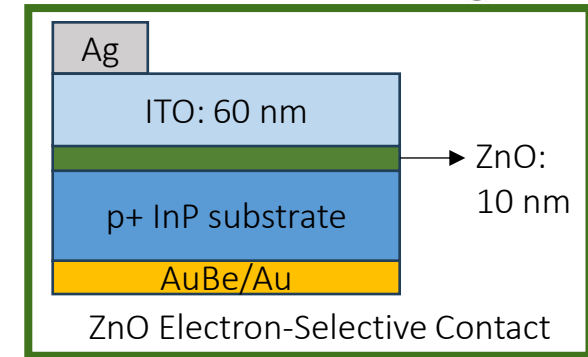
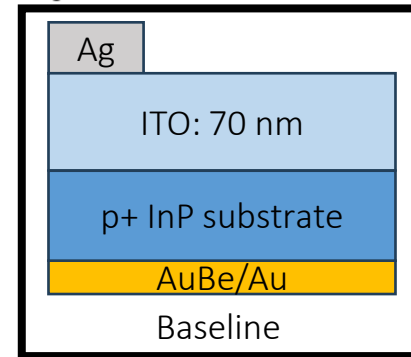
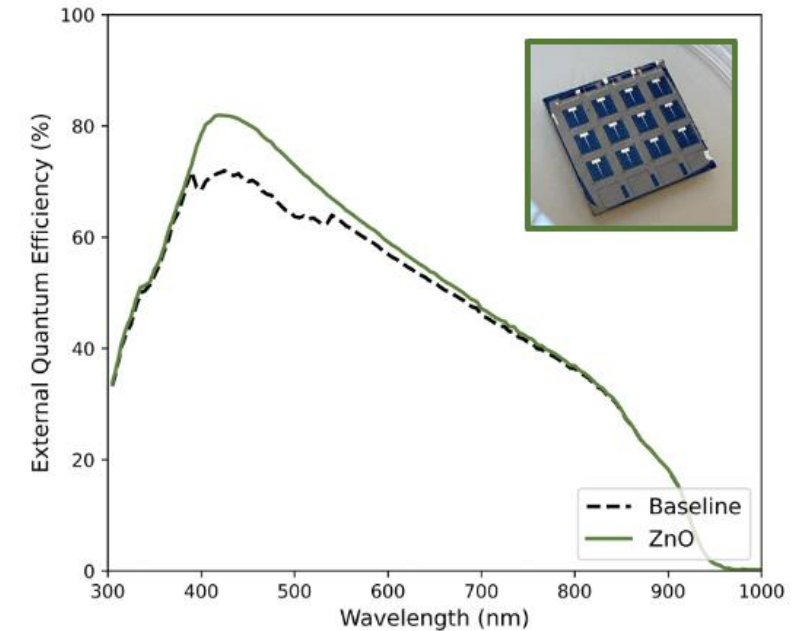
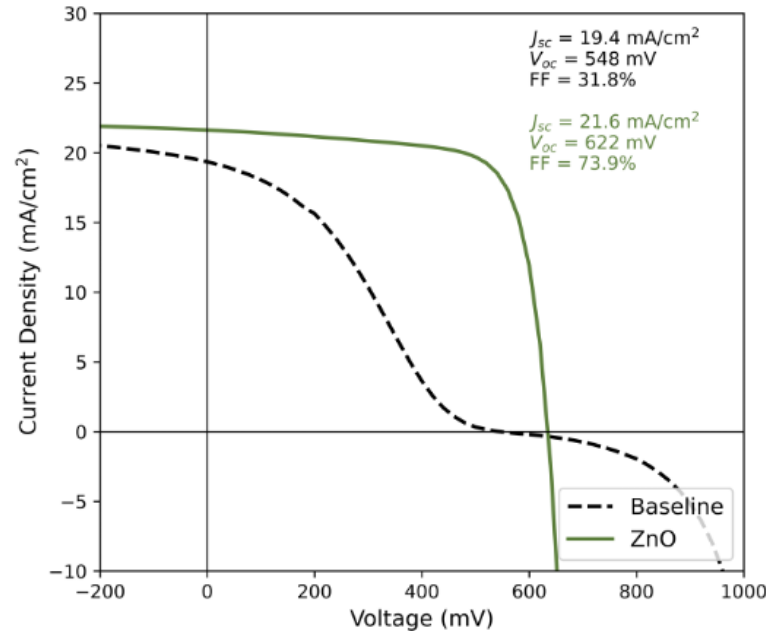
Reduced per gram cost of front contact material (Ag: \$0.55/g vs. Au: \$43/g)*

*Further development of Ni/Al front contact for space-grade is necessary

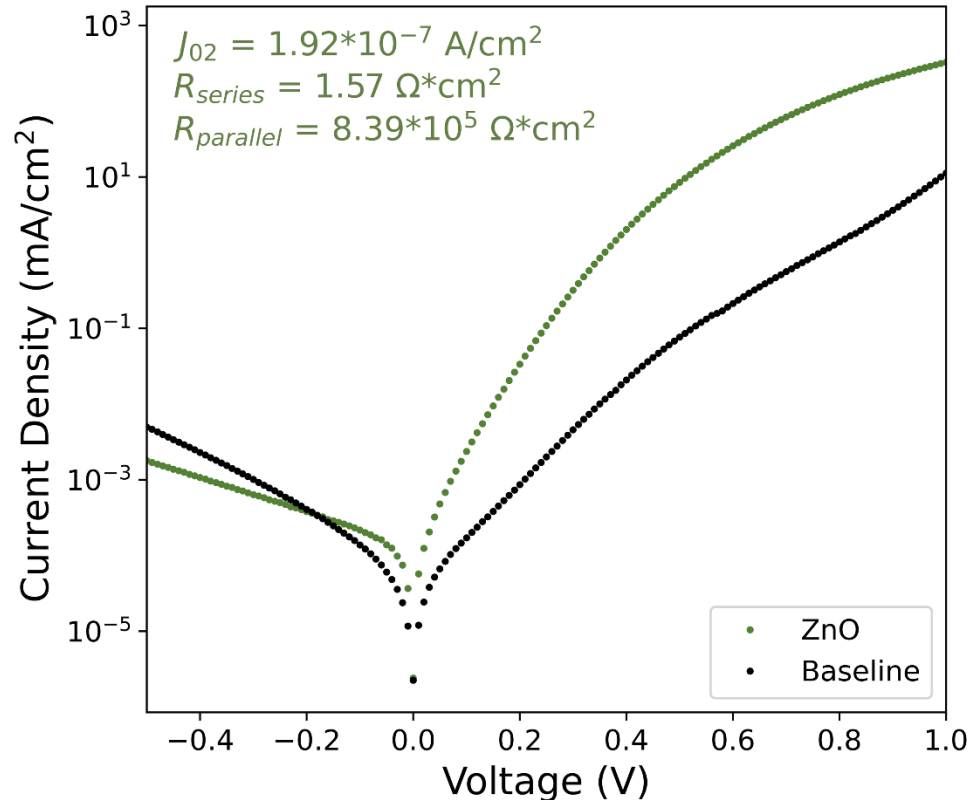
ZnO Electron-Selective Contact for InP

Cell efficiency of 7.27%

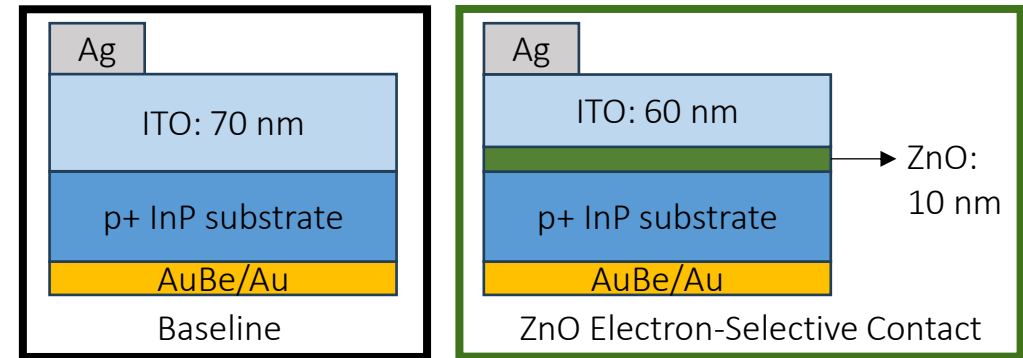
- ZnO clearly demonstrates barrier-free carrier extraction
- Without emitter thinning, ARC, or minimizing shading loss (10%)
- Record for fully sputtered InP device architecture (previously 6.02%)¹⁰



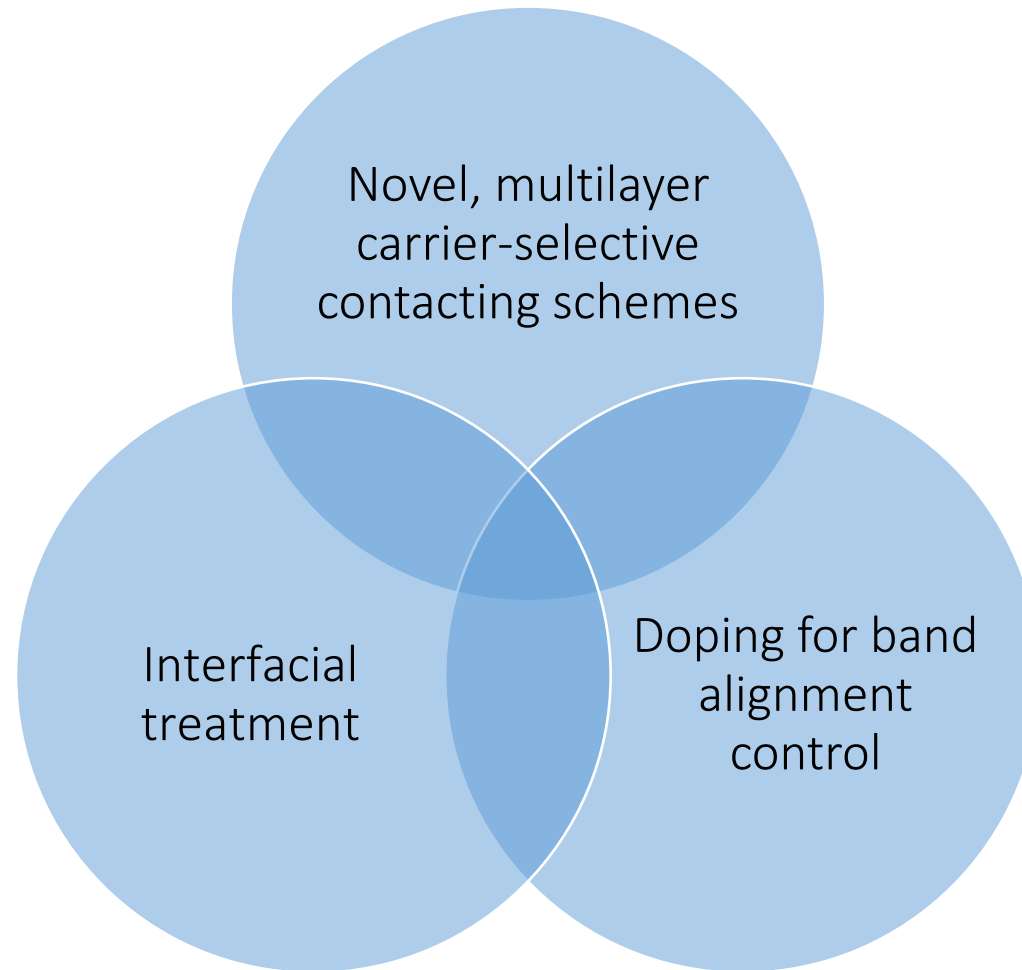
ZnO Electron-Selective Contact for InP



- Consistent sheet resistances of $\sim 67 \text{ } \Omega/\text{sq}$ for ITO
 - ZnO was too resistive to measure
- Maintains smooth surface morphologies, RMS roughness of 0.4 nm
- RF sputtering at low temperatures minimizes interfacial damage with uniform nanocrystalline ZnO coverage¹¹



Significant Potential for Advancement



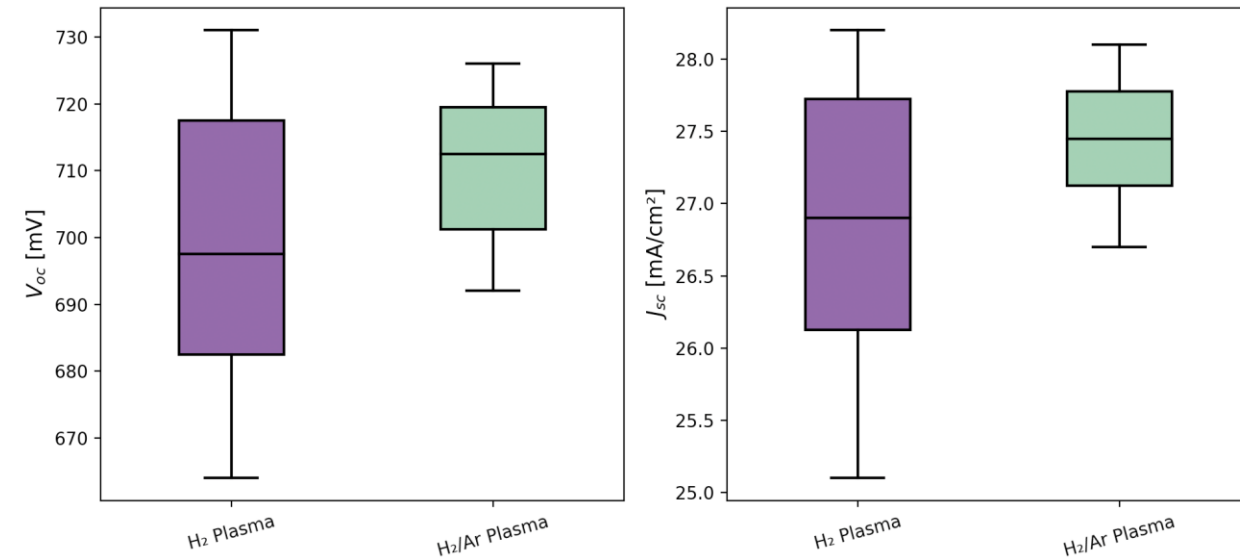
Interfacial Treatment – H₂ Plasma

Hydrogenation has been used to passivate shallow Zn acceptors and form a charge-depleted layer in the bulk¹²

- **Challenges:** Damaging InP surface (due to In-droplet formation) and difficult reproducibility¹²

Introducing Ar to stabilize H₂ plasma, mitigating surface roughening and lowered J₀₂ by an order of magnitude

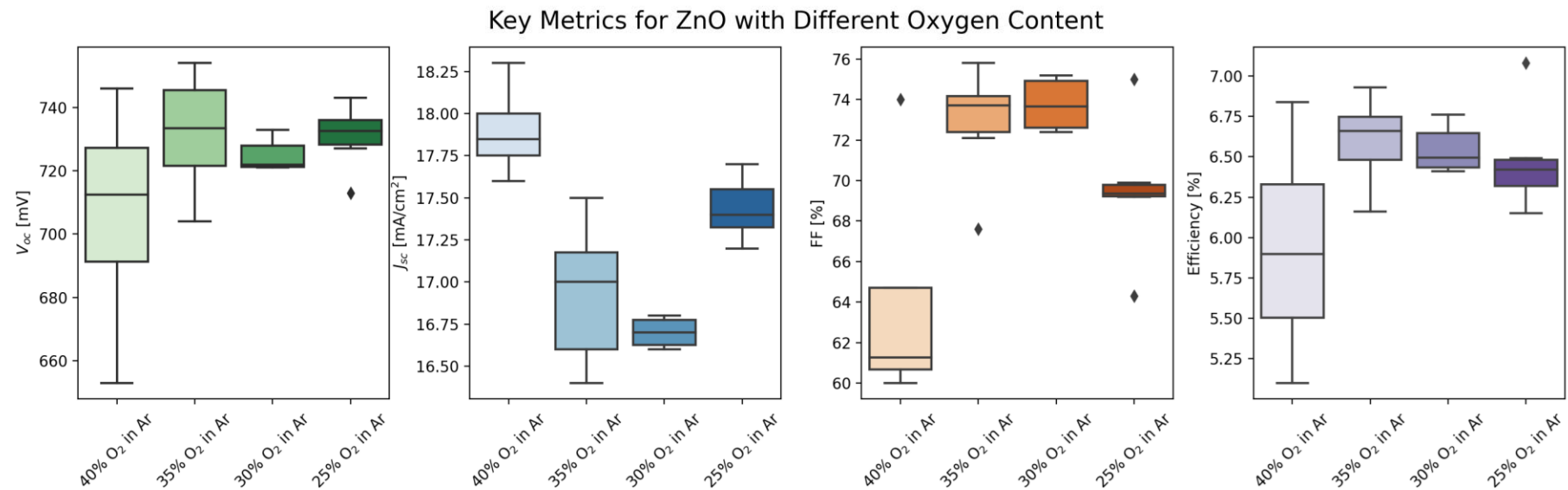
Variation across 1.5 cm × 1.5 cm chip



J_{sc} : 27.6 mA/cm²
 V_{oc} : 702 mV
FF: 76.1%
 η (AM0): 10.79%

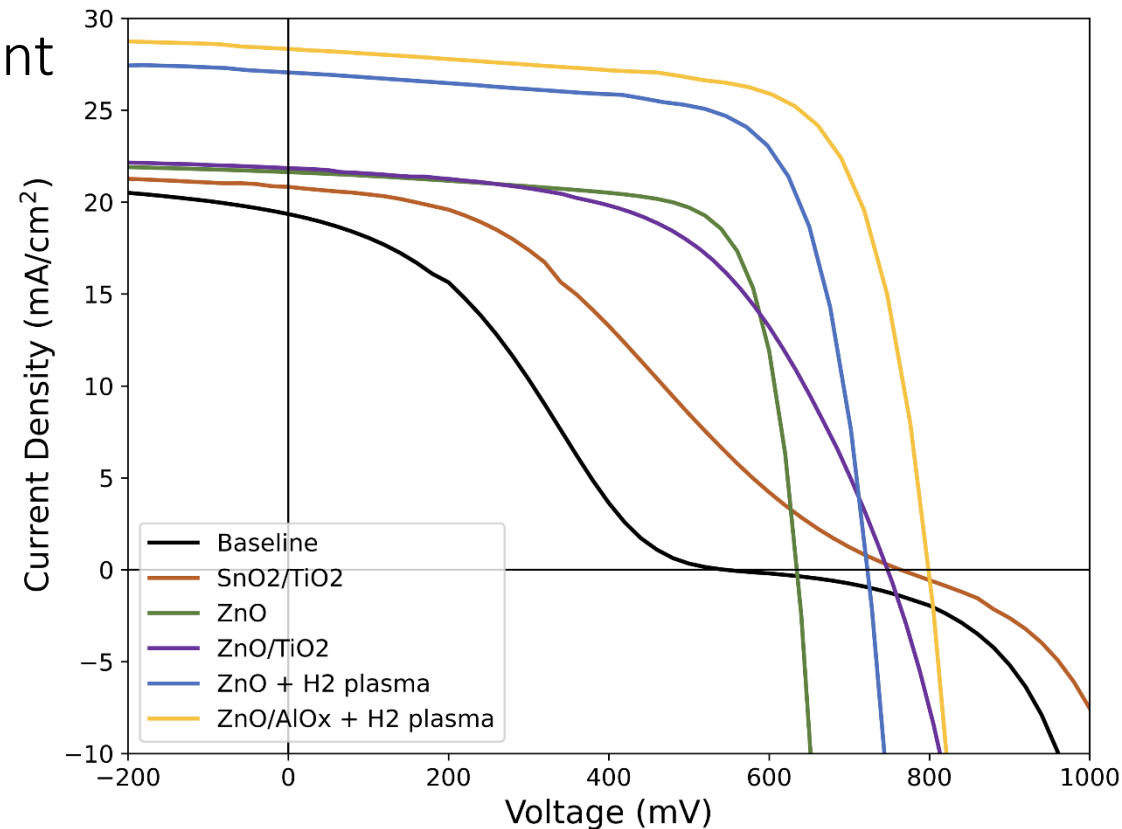
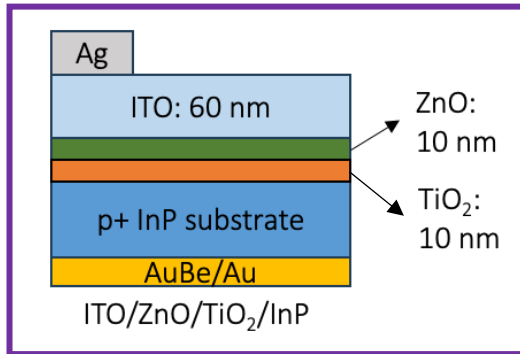
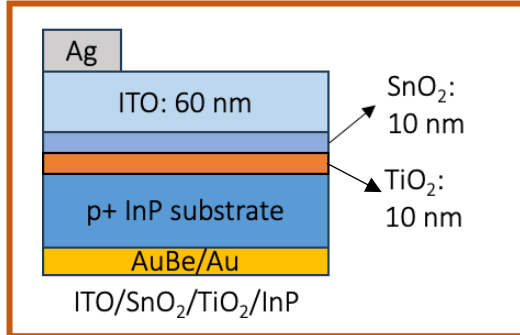
Oxygen Vacancy and Metal Doping

- Optimization of oxygen vacancies presents a **trade-off** between n-type conductivity, charge carrier transport, and increased visible light absorption
- Confirmed **bandgap narrowing** as increased oxygen vacancies using UPS

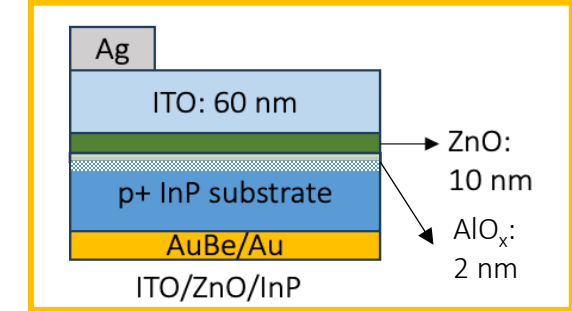


Multilayer Oxide Systems

Preliminary demonstration
of cascading band alignment
for increased V_{oc}



Attempting to decouple
passivation and carrier
extraction + H₂ plasma



J_{sc} : 28.8 mA/cm²
 V_{oc} : 809 mV
FF: 76.1%
 η (AM0): 12.91%

- Optimization of electron-selective contact
 - Going to **thinner ESC**
 - Optimizing **oxygen vacancy doping**
- **Improved passivation** of space charge region either through interfacial treatment or multilayer system
- **Radiation testing** for electronic stability of non-epitaxial device
- Immediate **pathway to 15% AM0 efficiency**:
 - Reduced front contact coverage
 - Addition of lower index ARC



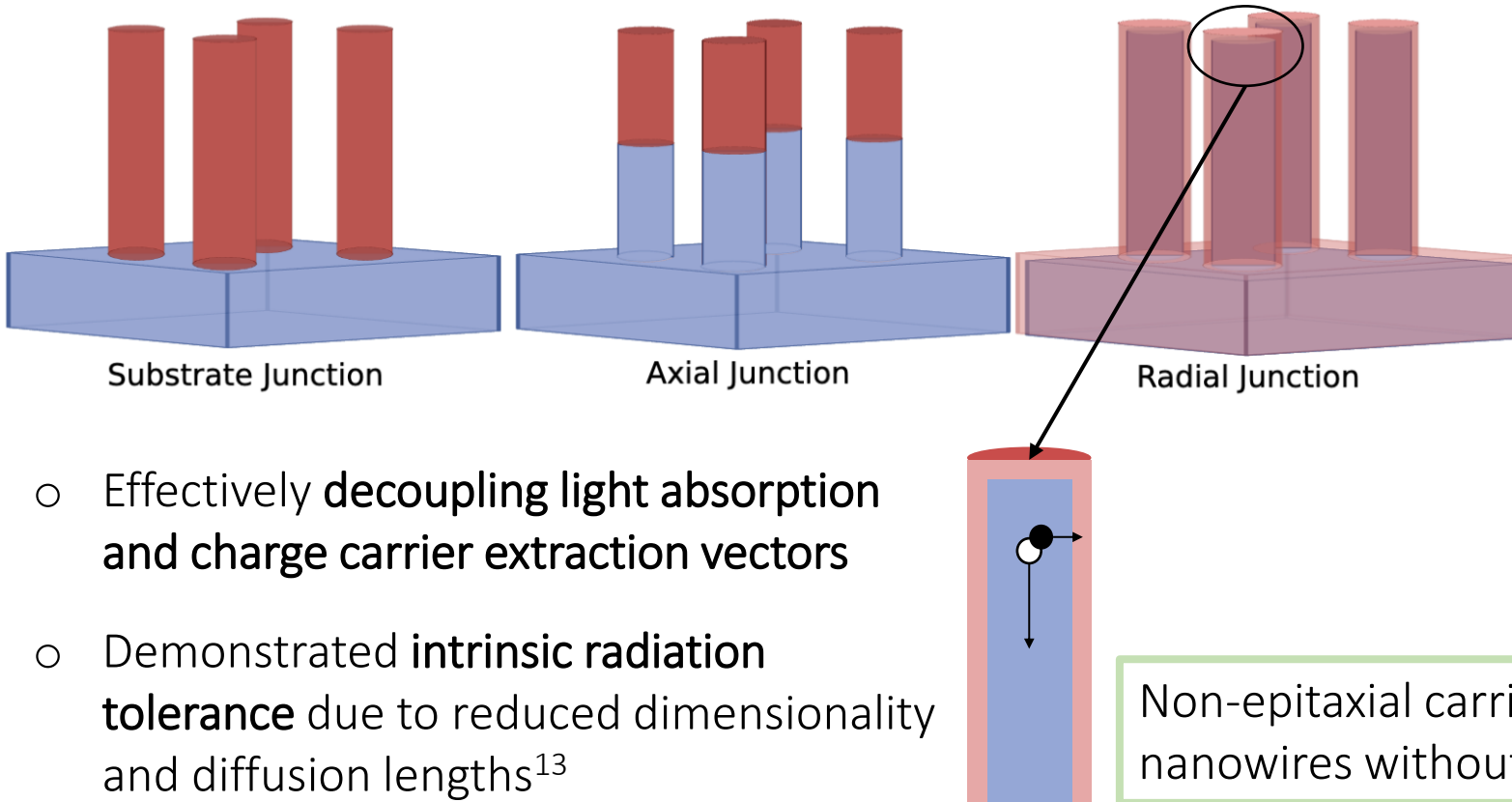
Radiation Tolerant Nanowire Solar Cells

Thinner Substrates/Spalled InP

Fundamental Challenges

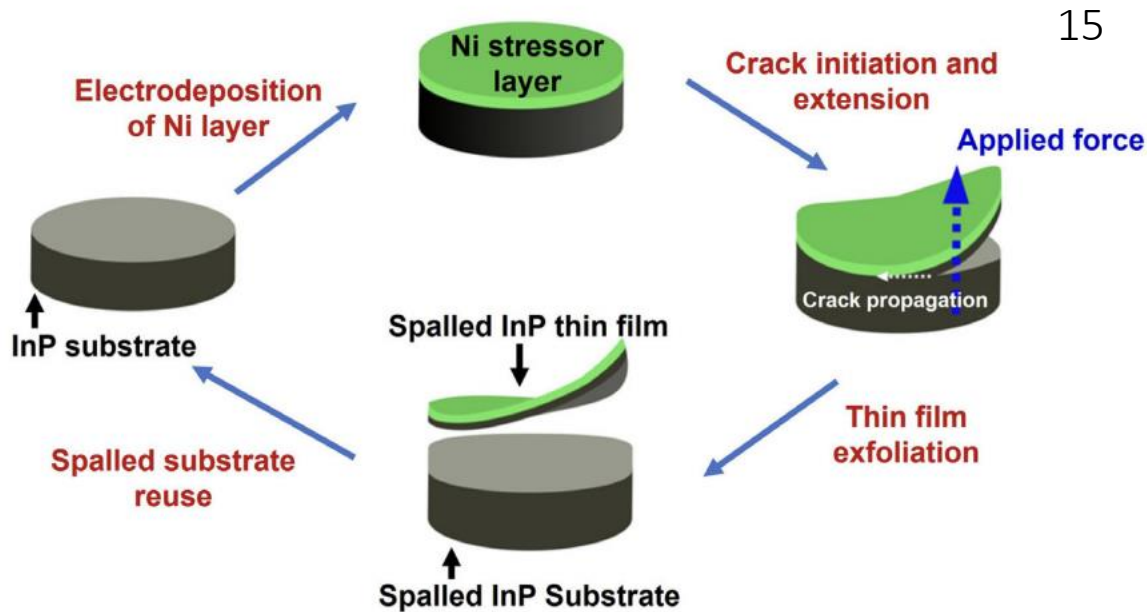
1. Reduced dimensionality results in **limited light absorption**
2. High surface-to-volume ratio results in higher **rates of non-radiative recombination** (defects)
3. Epitaxial dopant incorporation to form radial junctions is quite **complicated and variable**

- Effectively **decoupling light absorption and charge carrier extraction vectors**
- Demonstrated **intrinsic radiation tolerance** due to reduced dimensionality and diffusion lengths¹³



Non-epitaxial carrier-selective contacts enable radial junction nanowires without dopant incorporation

Radiation Tolerant Nanowire Solar Cells



Thinner Substrates/Spalled InP

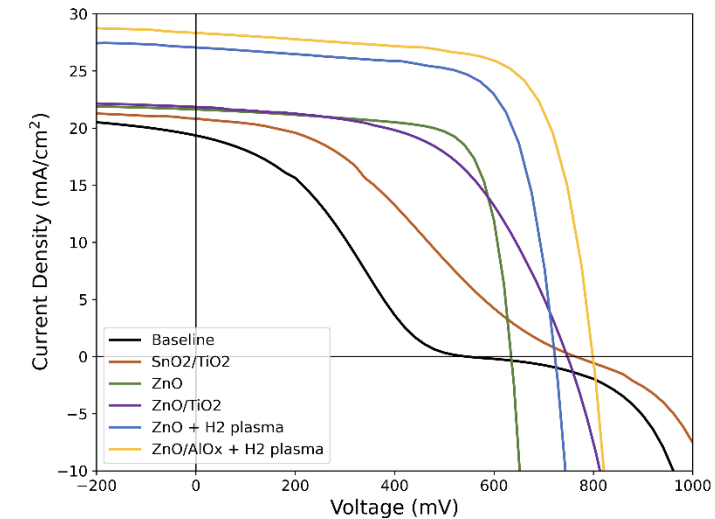
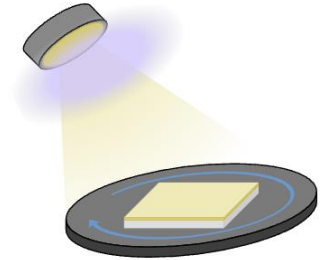
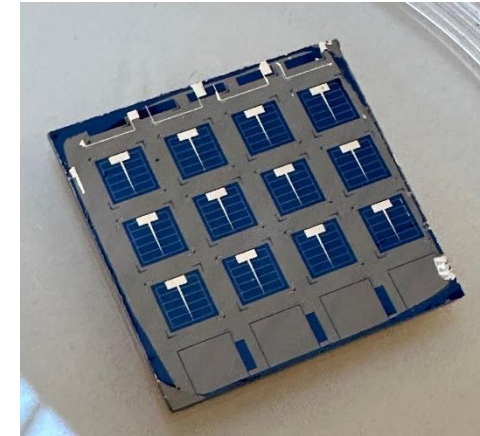
Integrating transition metal oxide-based carrier-selective contacts with spalled InP spalled thin films

- Reduced material cost
- Improved radiation tolerance from thinner substrates

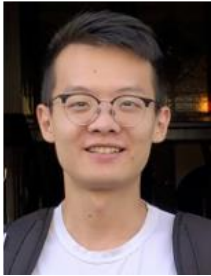
Preliminary results, using TiO_2 ALD, demonstrate 8.9% efficiency (under AM1.5) on 15 μm spalled InP thin film¹⁴

Conclusions

1. Present **7.27%** efficient (under AM0) fully sputtered InP solar cell using ZnO as an electron-selective contact
2. Demonstrate significant potential in cost-efficiency using less complex and industry scalable techniques
3. Highlight large parameter space and multiple pathways to enhanced device performance, with preliminary results achieving an efficiency of **12.91%**



Acknowledgements



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John M. Walls



Hannah Joyce



Louise Hirst



Get in touch!
vsac2@cam.ac.uk



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- Indium processed as zinc concentrate byproduct, **diffused in occurrence.**
- **Potential for distributed refining** but low market demand currently.
 - Gallium for comparison: significant export controls from China, which accounts for 99% of worldwide primary low-purity gallium production
- Lower toxicity and import regulation

<u>World Refinery Production and Capacity:</u>			<u>Indium</u>
	Refinery production		Refinery capacity
	<u>2023</u>	<u>2024^e</u>	<u>2024^e</u>
United States	—	—	—
Belgium	19	10	50
Canada	40	35	70
China	690	760	1,100
France	21	21	70
Japan	65	60	70
Korea, Republic of	180	180	310
Peru	—	—	50
Russia	5	10	15
Uzbekistan	1	1	1
World total (rounded)	1,020	1,080	1,800

<u>World Low-Purity Production and Production Capacity:</u>			<u>Gallium</u>
	Primary production		Production capacity
	<u>2023</u>	<u>2024^e</u>	<u>2024^e</u>
United States	—	—	—
China	⁴ 621,000	⁴ 750,000	1,000,000
Japan ^e	3,000	3,000	10,000
Korea, Republic of ^e	3,000	3,000	16,000
Russia ^e	6,000	6,000	10,000
Other countries ⁵	—	—	^e 88,000
World total (rounded)	633,000	760,000	^e 1,100,000

Designing Non-Epitaxial Carrier-Selective Contacts

Literature

Oxides	Device Type	J_{sc} [mA/cm ²]	V_{oc} [mV]	FF [%]	Efficiency [%]
¹ TiO ₂ /InP	Planar	30.5	785	80.5	19.2
* ² Ta ₂ O ₅ /InP	Planar	30.1	822	77	19.1
* ³ ZnO/InP	Planar	29.4	819	75.23	18.1
* ⁴ ZnO/GaAs	Planar	26.2	890	79.2	18.5
* ⁵ Ferri-hydrite/InP	Planar	28.6	761	76.2	16.6
⁶ ZnO/InP	Nanowire	31.3	736	74.6	17.1



Loughborough Oxide Thicknesses – Ellipsometry + AFM

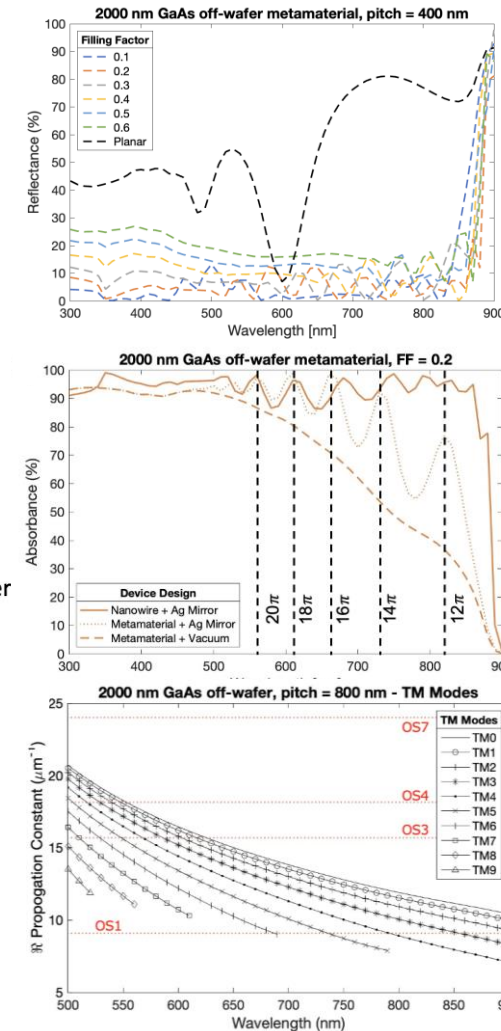
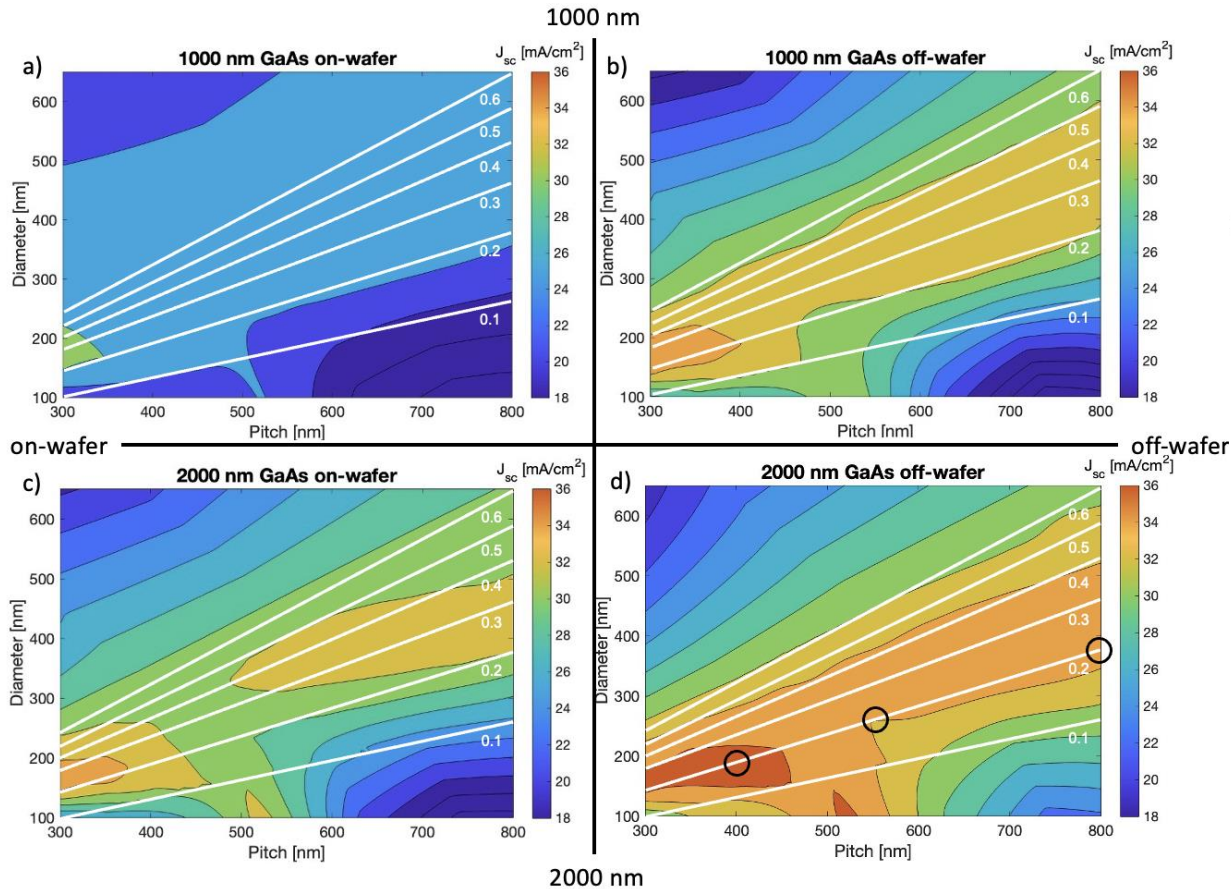
Oxide	Nominal Thickness (nm)	Fitted Thickness (nm)	Oxide Regrowth	Roughness (nm)	RMSE
ITO	60	66	Yes – 7.3nm	2.6	10.7
ITO	300				
ZnO	10	7.8	Hard to Distinguish	1.2	8.3

Surface	Substrate Temp. (°C)	O ₂ Content (% in Ar)	Nominal Thickness (nm)	RMS Roughness
Bare InP	-	-	-	1.03
ZnO	100	1	10	0.41
ITO	300	0.56	70	2.37



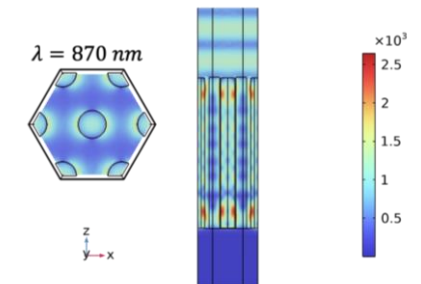
Field Enhancement through Engineered Light-Trapping

Design Space Screening using Full-Field Simulation



Deconvolution of light absorption by understanding individual mechanisms:

1. Reduced reflection at front surface
2. Fabry-Perot modes due to constructive interference of specular reflected waves
3. Identify individual waveguide modes from scattering



$d = 188 \text{ nm}$, pitch = 400 nm – HE_{11} mode

